

Oblon, Spivak, et al.
New CONT Application
Inv: Takashi YAMADA, et al.
Preliminary Amendment

Amendments to the Specification:

Please replace the existing title with the following new title:

SEMICONDUCTOR CHIP WHICH COMBINES BULK AND SOI REGIONS AND
SEPARATES SAME WITH PLURAL ISOLATION REGIONS

Please replace the paragraph at page 1, lines 5-7, with the following amended paragraph:

This patent application is based upon and claims the benefit of the earlier filing date of Japanese Patent Application No. 2001-298533, filed September 27, 2001, and from U.S. Application No. 09/995,594, filed November 29, 2001, the entire contents of which are incorporated herein by reference.